

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BTS5030-2EKA	**Issued**	29. August 2013
MA#	MA001130774		
Package	PG-DSO-14-40	**Weight***	149.85 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.425	2.29	2.29	22853	22853
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		464	
	non noble metal	iron	7439-89-6	1.392	0.93		9288	
	non noble metal	copper	7440-50-8	56.512	37.71	38.70	377127	386995
wire	non noble metal	copper	7440-50-8	0.955	0.64	0.64	6373	6373
encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1119	
	plastics	epoxy resin	-	7.711	5.15		51462	
	inorganic material	silicondioxide	60676-86-0	75.941	50.66	55.92	506788	559369
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8183	8183
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9460	9460
glue	plastics	epoxy resin	-	0.177	0.12		1184	
	noble metal	silver	7440-22-4	0.837	0.56	0.68	5583	6767
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com